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Siliup Semiconductor

SP40N02GNK

40V N-Channel Power MOSFET

Product Summary

$V_{(BR)DSS}$	$R_{DS(on)TYP}$	I_D
40V	1.9mΩ@10V	120A
	2.7mΩ@4.5V	

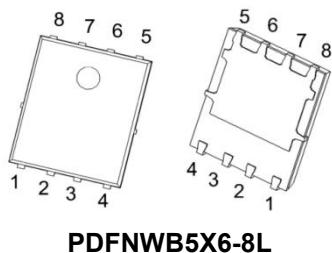
Feature

- Fast Switching
- Low Gate Charge and Rdson
- 100% Single Pulse avalanche energy Test

Applications

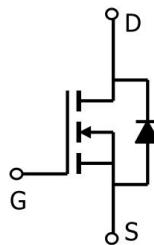
- DC-DC Converter
- Ideal for high-frequency switching and synchronous rectification

Package

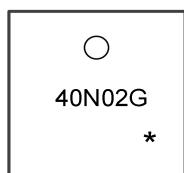


PDFNWB5X6-8L

Circuit diagram



Marking



40N02G
*

=Device Code
=Month Code



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Absolute maximum ratings (Ta=25°C,unless otherwise noted)

Parameter	Symbol	Rating	Units
Drain-Source Voltage	V _{DS}	40	V
Gate-Source Voltage	V _{GS}	±20	V
Continuous Drain Current ¹ (T _C =25°C, Package limit)	I _D	120	A
Continuous Drain Current ¹ (T _C =25°C, Silicon limit)	I _D	210	A
Pulsed Drain Current ²	I _{DM}	480	A
Single Pulse Avalanche Energy ³	E _{AS}	529	mJ
Total Power Dissipation ⁴ (T _C =25°C)	P _D	120	W
Thermal Resistance Junction-Case ¹	R _{θJC}	1.04	°C/W
Storage Temperature Range	T _{STG}	-55 to 150	°C
Operating Junction Temperature Range	T _J	-55 to 150	°C

Electrical characteristics (Ta=25°C, unless otherwise noted)

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
Static Characteristics						
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V , ID=250uA	40	---	---	V
Drain-Source Leakage Current	I _{DSS}	V _{DS} =32V , V _{GS} =0V , T _J =25°C	---	---	1	uA
Gate-Source Leakage Current	I _{GSS}	V _{GS} =±20V , V _{DS} =0V	---	---	±100	nA
Gate Threshold Voltage	V _{GS(th)}	V _{GS} =V _{DS} , ID =250uA	2	3	4	V
Static Drain-Source On-Resistance ²	R _{DS(ON)}	V _{GS} =10V , ID=30A	---	1.9	2.4	mΩ
		V _{GS} =4.5V , ID=20A	---	2.7	3.6	
Dynamic characteristics						
Input Capacitance	C _{iss}	V _{DS} =20V , V _{GS} =0V , f=1MHz	---	3485	---	pF
Output Capacitance	C _{oss}		---	1208	---	
Reverse Transfer Capacitance	C _{rss}		---	59	---	
Switching Characteristics						
Total Gate Charge	Q _g	V _{DS} =20V , V _{GS} =10V , ID=65A	---	57	---	nC
Gate-Source Charge	Q _{gs}		---	9.5	---	
Gate-Drain Charge	Q _{gd}		---	11	---	
Turn-On Delay Time	T _{d(on)}	VDD=20V , VGS=10V , RG=1.6Ω, ID=65A	---	10	---	ns
Rise Time	T _r		---	3	---	
Turn-Off Delay Time	T _{d(off)}		---	35	---	
Fall Time	T _f		---	4	---	
Diode Characteristics						
Diode Forward Voltage ²	V _{SD}	V _{GS} =0V , IS=20A , T _J =25°C	---	---	1.2	V

Note :

1. The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.
2. The data tested by pulsed , pulse width ≤ 300us , duty cycle ≤ 2%
3. The EAS data shows Max. rating . The test condition is VDD=15V,VGS=10V,L=0.5mH,RG=25Ω



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Typical Characteristics

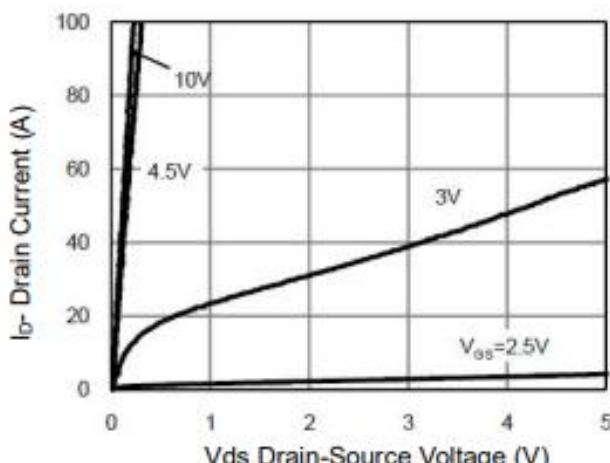


Figure 1 Output Characteristics

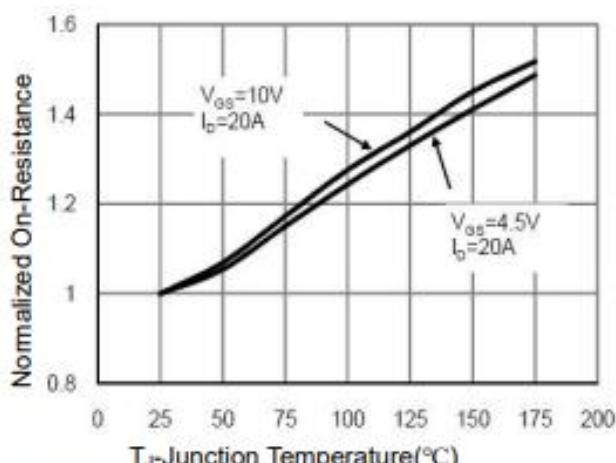


Figure 4 Rdson-Junction Temperature

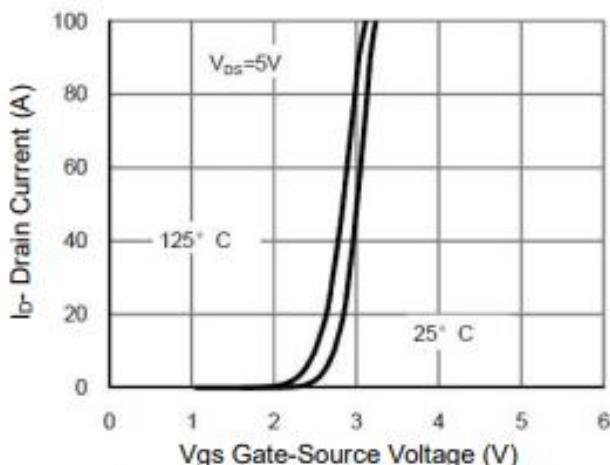


Figure 2 Transfer Characteristics

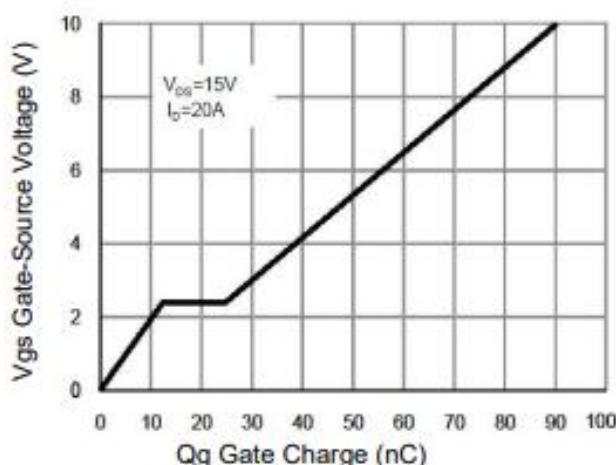


Figure 5 Gate Charge

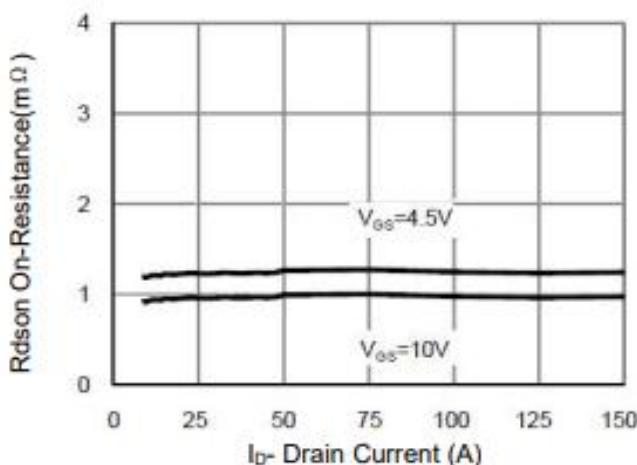


Figure 3 Rdson- Drain Current

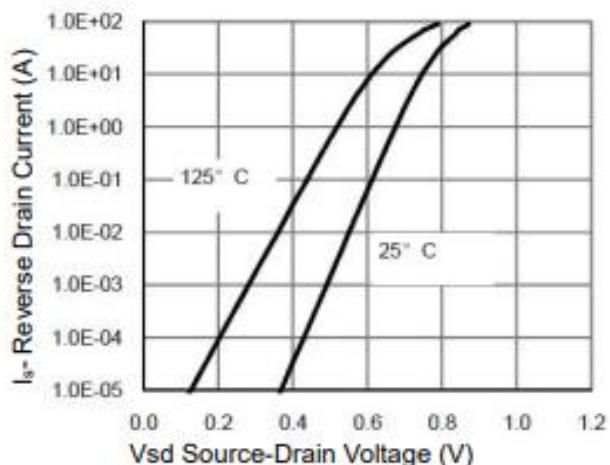


Figure 6 Source- Drain Diode Forward



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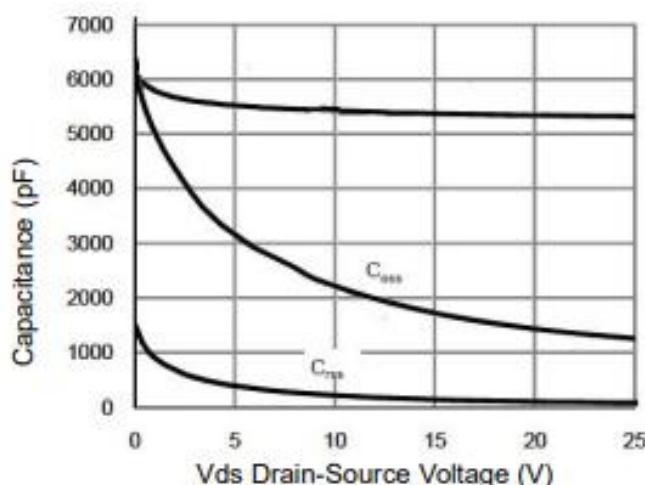


Figure 7 Capacitance vs Vds

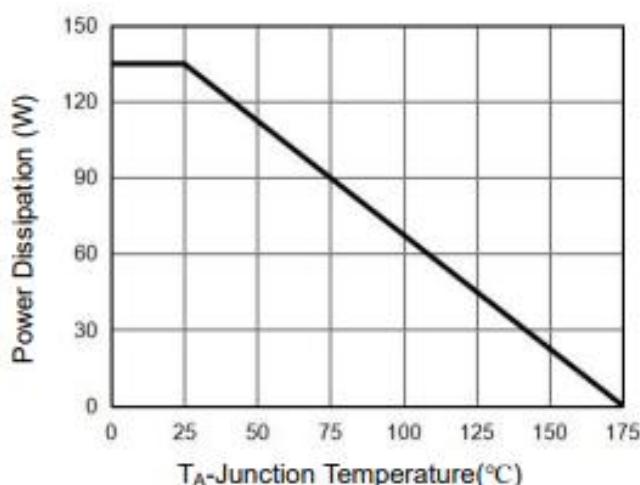


Figure 9 Power De-rating

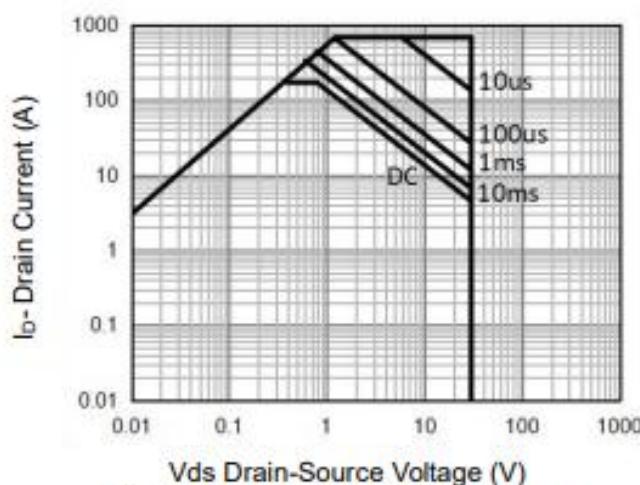


Figure 8 Safe Operation Area (Note3)

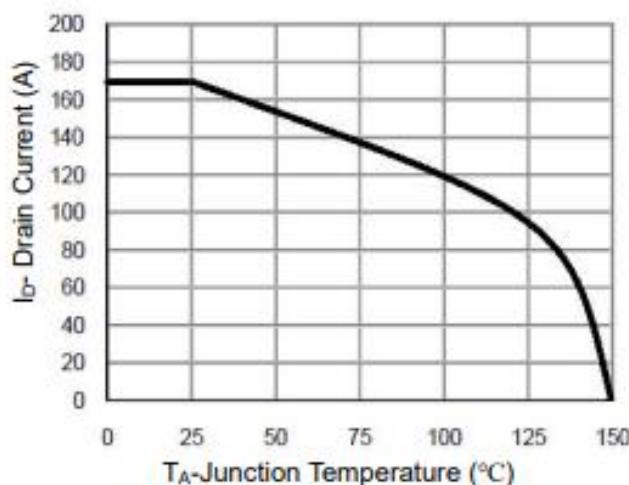


Figure 10 Current De-rating

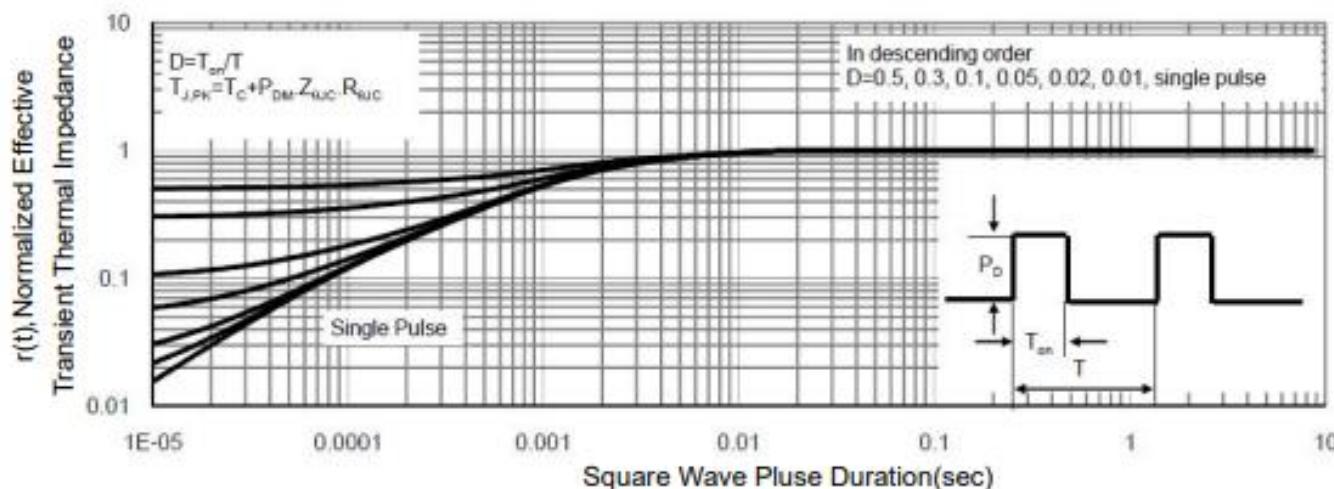


Figure 11 Normalized Maximum Transient Thermal Impedance

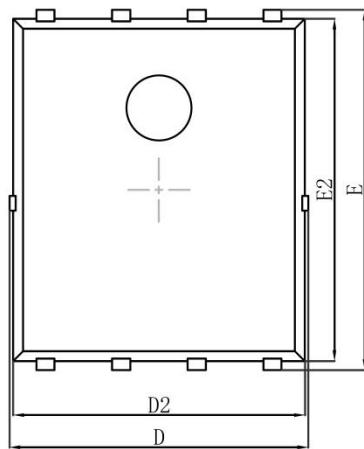
PDFNWB5X6-8L Package Information



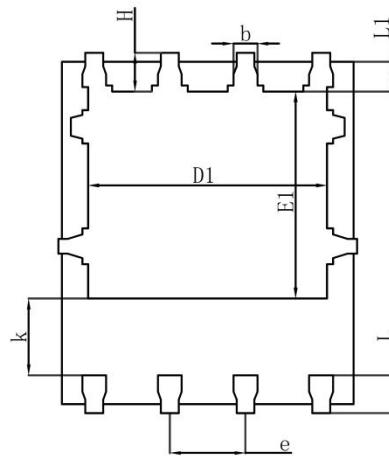
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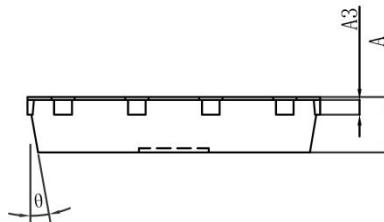
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Top View
[顶视图]



Bottom View
[背视图]



Side View
[侧视图]

Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	0.900	1.000	0.035	0.039
A3	0.254REF.		0.010REF.	
D	4.944	5.096	0.195	0.201
E	5.974	6.126	0.235	0.241
D1	3.910	4.110	0.154	0.162
E1	3.375	3.575	0.133	0.141
D2	4.824	4.976	0.190	0.196
E2	5.674	5.826	0.223	0.229
k	1.190	1.390	0.047	0.055
b	0.350	0.450	0.014	0.018
e	1.270TYP.		0.050TYP.	
L	0.559	0.711	0.022	0.028
L1	0.424	0.576	0.017	0.023
H	0.574	0.726	0.023	0.029
θ	10°	12°	10°	12°